

PMP8411 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB100	1		Use PMP8411 REVA	Any	Printed Circuit Board	
C1_1, C2_1,	6	1000pF	C1005C0G1E102J	TDK	CAP, CERM, 1000 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
C5_1, C5_2,						
C24_1, C24_2						
C3_1	1	470pF	C1005C0G1H471J	TDK	CAP, CERM, 470 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C4_1, C4_2	2	0.1uF	C1005X7R1H104K	TDK	CAP, CERM, 0.1 μF, 50 V, +/- 10%, C0G/NP0, 0402	0402
C6_1, C6_2,	12	100uF	GRM32EC80J107ME20L	MuRata	CAP, CERM, 100 μF, 6.3 V, +/- 20%, X6S, 1210	1210
C7_1, C7_2,						
C8_1, C8_2,						
C19_1, C19_2,						
C20_1, C20_2,						
C21_1, C21_2						
C9_1, C9_2,	8	22uF	GRM32ER61C226KE20L	MuRata	CAP, CERM, 22 µF, 16 V, +/- 10%, X5R, 1210	1210
C10_1, C10_2,						
C11_1, C11_2,						
C12_1, C12_2						2222
C13_1, C13_2	2	2.2uF	GRM188R61C225KAAD	MuRata	CAP, CERM, 2.2 μF, 16 V, +/- 10%, X5R, 0603	0603
C14_1, C14_2,	6	1uF	C1608X5R1E105K080AC	TDK	CAP, CERM, 1 μF, 25 V, +/- 10%, X5R, 0603	0603
C16_1, C16_2,						
C17_1, C17_2			0.400=3/=0.4000.4/0=0000		0.00 0.00 E 40.0 / 400/ VED 0.400	0.100
C15_1, C15_2,	4	0.22uF	C1005X7R1C224K050BC	TDK	CAP, CERM, 0.22 μF, 16 V, +/- 10%, X7R, 0402	0402
C18_1, C18_2	4	4 5	0400577500 140574	TDV	0AD 0EDM 4 E 0.0 V 1/ 000/ VED 0400	0.400
C22_1, C22_2,	4	1uF	C1005X5R0J105M	TDK	CAP, CERM, 1 μF, 6.3 V, +/- 20%, X5R, 0402	0402
C23_1, C23_2	0	47	TD0D470M040D0000	A \ / \ /	CAD TA 47 vF 40 V v/ 000/ 0 00 abra CMD	70.40.04
C25_1, C25_2,	8	47uF	TPSD476M016R0080	AVX	CAP, TA, 47 μF, 16 V, +/- 20%, 0.08 ohm, SMD	7343-31
C26_1, C26_2,						
C27_1, C27_2, C28_1, C28_2						
C29_1, C29_2,	8	470uF	4TPE470MAL	Panasonic	CAP, TA, 470 μF, 4 V, +/- 20%, 0.01 ohm, SMD	7.3x2.8x4.3mm
C30_1, C30_2,		47001	417 E47 OWAL	r aliasoffic	ολι, τλ, 470 μι, 4 V, +/- 20 /0, 0.01 οππ, οινίο	7.382.084.311111
C31_1, C31_2,						
C32_1, C32_2						
C100	1	470uF	16SVPE470M	Panasonic	CAP, AL, 470 μF, 16 V, +/- 20%, 0.01 ohm, SMD	JC0
FID100, FID101	2	17 001	N/A	N/A	Fiducial mark. There is nothing to buy or mount.	Fiducial
J1_1, J1_2	2		U.FL-R-SMT-1	Hirose Electric Co. Ltd.	Connector, Ultra-Mini Coaxial, SMD	Ultra small CO-AX
	_					SMD
J100, J101, J102	3		1715747	Phoenix Contact	Terminal Block, 5.08mm, 4x1, TH	Terminal Block,
			1			5.08mm, 4x1, TH
J103, J104, J105	3		800-10-002-10-001000	Mill-Max	Header, 100mil, 2x1, TH	Header, 2x1, 100mil,
					, , , , , , , , , , , , , , , , , , , ,	TH
J106	1		N2510-6002-RB	3M	Header (shrouded), 100mil, 5x2, High-Temperature, Gold, TH	5x2 Shrouded header
J107	1		TSW-104-07-G-S	Samtec	Header, 100mil, 4x1, Gold, TH	4x1 Header
R1_1	1	511	CRCW0402511RFKED	Vishay-Dale	RES, 511, 1%, 0.063 W, 0402	0402
R2_1, R12_1,	3	10.0k	PCF0402-12-10KBT1	TT Electronics/IRC	RES, 10.0 k, 0.1%, 0.063 W, 0402	0402
R12_2						

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R4_1, R13_1,	5	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0, 1%, 0.063 W, 0402	0402
R13_2, R14_1,		10.0	ONO 102 TOTAL TREE	Violity Balo	1125, 10.0, 170, 0.000 11, 0.102	0 102
R14_2						
R5_1, R10_2	2	0	ERJ-2GE0R00X	Panasonic	RES, 0, 5%, 0.063 W, 0402	0402
R6_1	1	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R7_1	1	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402
R9_1, R9_2	2	49.9	CRCW040249R9FKED	Vishay-Dale	RES, 49.9, 1%, 0.063 W, 0402	0402
R11_1, R11_2	2	49.9k	CRCW040249K9FKED	Vishay-Dale	RES, 49.9 k, 1%, 0.063 W, 0402	0402
R15_1, R15_2,	3	38.3k	CRCW040238K3FKED	Vishay-Dale	RES, 38.3 k, 1%, 0.063 W, 0402	0402
R16_1						
R16_2	1	53.6k	CRCW040253K6FKED	Vishay-Dale	RES, 53.6 k, 1%, 0.063 W, 0402	0402
R103, R104	2	100	RG1005P-101-B-T5	Susumu Co Ltd	RES, 100, 0.1%, 0.063 W, 0402	0402
U1_1, U1_2	2		OKLP-X/45-W12-C	MuRata	45A Power Block Non-Isolated DC/DC Converter, SMD, Body 25.4 x 12.7	Module, 25.4x12.7mm
					mm	
U2_1, U2_2	2		TPS40425RHA	Texas Instruments	Dual output, 2-Phase, Stackable PMBUS Synchronous Buck Driverless	RHA0040B
					Controller with AVS Bus, RHA0040B	
C1_2, C2_2	0	1000pF	C1005C0G1E102J	TDK	CAP, CERM, 1000 pF, 25 V, +/- 5%, C0G/NP0, 0402	0402
C3_2	0	470pF	C1005C0G1H471J	TDK	CAP, CERM, 470 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
R1_2	0	511	CRCW0402511RFKED	Vishay-Dale	RES, 511, 1%, 0.063 W, 0402	0402
R2_2	0	10.0k	PCF0402-12-10KBT1	TT Electronics/IRC	RES, 10.0 k, 0.1%, 0.063 W, 0402	0402
R3_1, R3_2,	0	100k	CRCW0402100KFKED	Vishay-Dale	RES, 100 k, 1%, 0.063 W, 0402	0402
R8_1, R8_2						
R4_2	0	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0, 1%, 0.063 W, 0402	0402
R5_2, R10_1	0	0	ERJ-2GE0R00X	Panasonic	RES, 0, 5%, 0.063 W, 0402	0402
R6_2	0	10.0k	CRCW040210K0FKED	Vishay-Dale	RES, 10.0 k, 1%, 0.063 W, 0402	0402
R7_2	0	20.0k	CRCW040220K0FKED	Vishay-Dale	RES, 20.0 k, 1%, 0.063 W, 0402	0402

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